

Optimizing ammonia-based MBE for gallium nitride electron mobility

University of California Santa Barbara and National Taiwan University have claimed the highest room-temperature bulk GaN mobility reported to date.

University of California Santa Barbara (UCSB) and National Taiwan University (NTU) have been optimizing ammonia-based molecular beam epitaxy (MBE) for gallium nitride (GaN) growth on a range of substrates [Erin C. H. Kyle et al, *J. Appl. Phys.*, vol115, p193702, 2014].

The researchers claim their highest single-die electron mobility of $1265 \text{ cm}^2/\text{Vs}$ at 296K ('room temperature', RT) for films grown on low-threading-dislocation-density (TDD) free-standing (FS) GaN templates as "the highest RT bulk GaN electron mobility to date". To back up the claim, the paper quotes a number of results from other groups (Table 1).

The researchers used a Veeco Gen 930 molecular beam epitaxy system with an unheated showerhead injector for the delivery of purified ammonia (NH_3). The gallium, silicon and magnesium came from standard effusion cells.

The templates were isolated from the active region of the bulk GaN by a structure consisting of an intrinsic layer sandwiched between lightly and heavily Mg-doped p-type GaN regions (Figure 1). The isolation ensured that negligible current flowed through the template or re-growth interface. Heavily Mg-doped

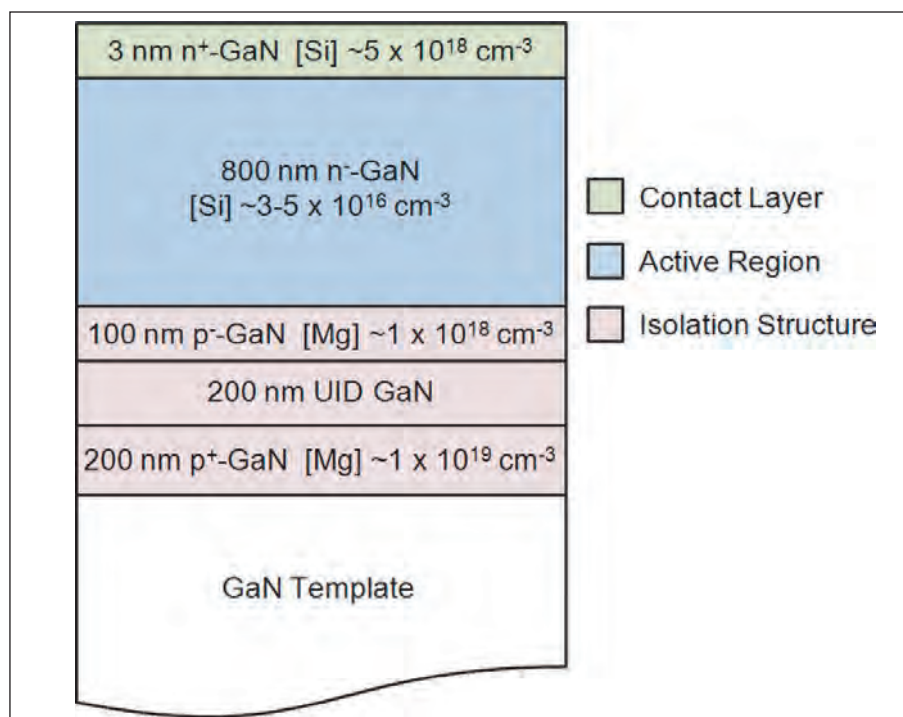


Figure 1. Schematic of UCSB/NTU growth structure.

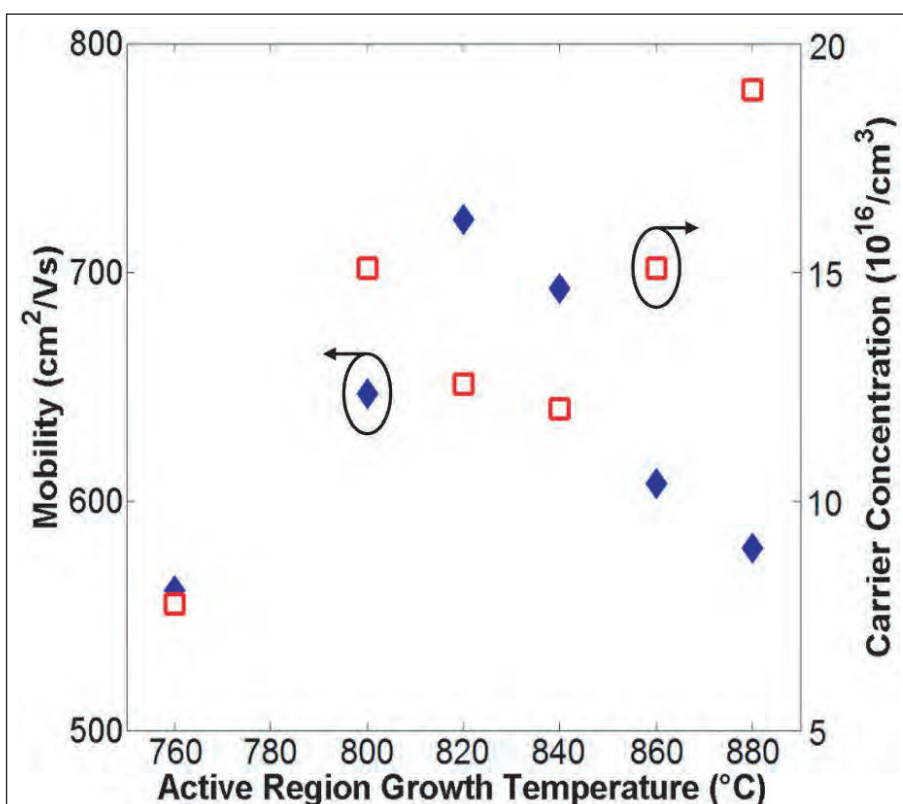


Figure 2. Average bulk electron mobility (solid blue diamonds) and average carrier concentration (red open squares) versus Active Region Growth Temperature ($^{\circ}\text{C}$).

GaN tends to result in rough surfaces. The undoped and lightly doped top layers of the isolation gave a smooth surface for further growth.

The bulk of the structure consisted of lightly Si-doped n-type GaN with a final layer of heavily doped material "to facilitate the formation of high-quality low-resistance ohmic contacts".

The growth was optimized with respect to temperature (760–880°C) and Si-doping concentration ($\sim 3 \times 10^{16}$ – $\sim 2 \times 10^{20}/\text{cm}^3$). Lumilog provided the semi-insulating iron-doped GaN:Fe on sapphire templates. The ammonia flow rate during optimization was 200 standard cubic centimeters (SCCM), giving a growth rate of 7.4nm/minute. The highest mobility of more than $700\text{cm}^2/\text{V-s}$ occurred in 820°C growth (Figure 2). The optimum silicon doping was found to be $\sim 3 \times 10^{16}/\text{cm}^3$ (Figure 3). Mobility decreases with increased doping, while some doping is needed to make an ohmic contact with metal electrodes.

Further experiments (Table 2) involved growth on a variety of templates where the ammonia flow rate was 200 or 1000 (SCCM) with the aim of quantifying the effects of TDDs. Naturally, the highest-mobility results came from using free-standing GaN templates with low TDDs. The researchers carried out a wide range of experimental and theoretical analyses to explore the impact of TDDs on the electrical performance of the GaN film. ■

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Author: Mike Cooke

Table 1. Room-temperature mobility of GaN grown by a variety of methods by different groups.

Method	Mobility ($\text{cm}^2/\text{V-s}$)	Year
HVPE	1245	2001
MOCVD	1005	2006
Ammonothermal	265	2007
N-rich PAMBE	1150	2007
Ga-rich PAMBE	1191	2000
NH_3 -MBE	560	1999
UCSB/NTU	1265	2014

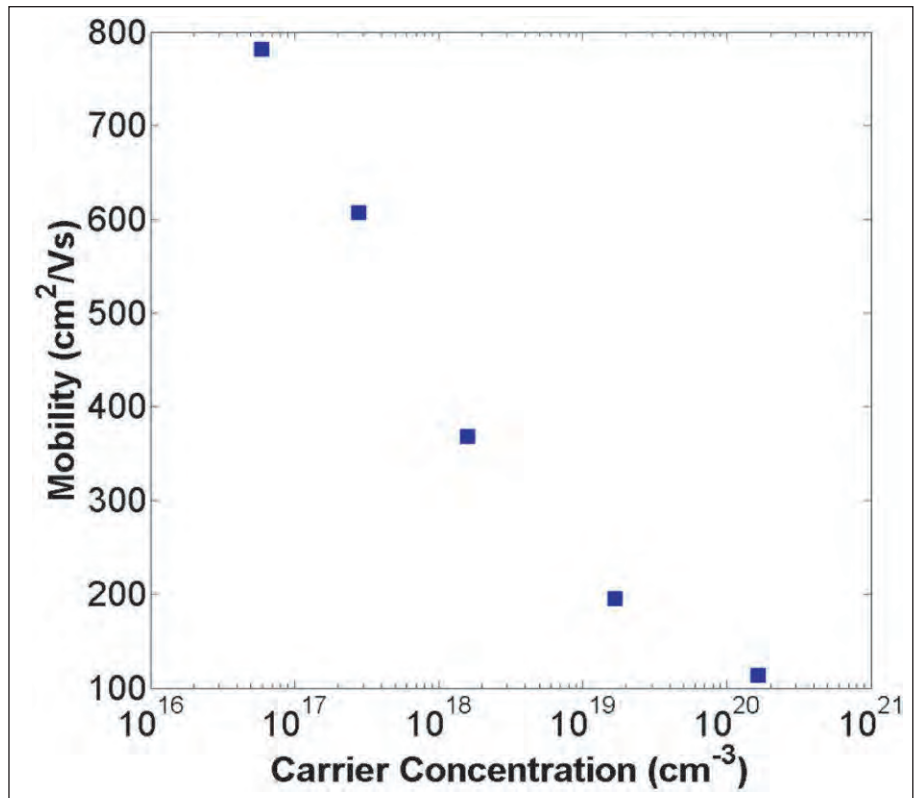


Figure 3. Effect of carrier concentration on electron mobility for GaN grown with optimized growth conditions.

Table 2. Single-die Hall measurements for 200SCCM and 100SCCM ammonia flow TDD series. Full-width at half maximum (FWHM) is for ω -scan x-ray diffraction from GaN (20 $\bar{2}$ 1) planes.

TDD-200 Series

TDD ($/\text{cm}^2$)	RT mobility (cm^2/Vs)	RT carrier concentration ($/\text{cm}^3$)	Highest mobility (cm^2/Vs)	Highest mobility temp. (K)	FWHM (arcsec)
$\sim 3 \times 10^7$	1256	4.48×10^{16}	2948	116	225
$\sim 5 \times 10^8$	961	3.50×10^{16}	2396	115	382
$\sim 5 \times 10^9$	204	4.9×10^{16}	343	154	739

TDD-1000 Series

TDD ($/\text{cm}^2$)	RT mobility (cm^2/Vs)	RT carrier concentration ($/\text{cm}^3$)	Highest mobility (cm^2/Vs)	Highest mobility temp. (K)	FWHM (arcsec)
$\sim 2 \times 10^6$	1265	3.73×10^{16}	3327	113	90
$\sim 5 \times 10^8$	966	2.09×10^{16}	2637	112	375
$\sim 2 \times 10^{10}$	317	1.33×10^{17}	348	212	1370